



NX3008NBKW

30 V, 350 mA N-channel Trench MOSFET

5 November 2022

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a very small SOT323 (SC70) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Very fast switching
- Low threshold voltage
- Trench MOSFET technology
- ESD protection up to 2 kV
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

4. Quick reference data

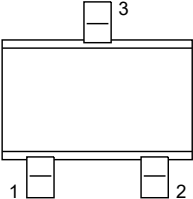
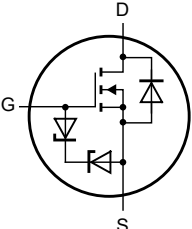
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$	-	-	30	V
V_{GS}	gate-source voltage		-8	-	8	V
I_D	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	350	mA
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}; I_D = 350\text{ mA}; T_j = 25\text{ °C}$	-	1	1.4	Ω

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 SC-70 (SOT323)	 017aaa255
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
NX3008NBKW	SC-70	plastic, surface-mounted package; 3 leads; 1.3 mm pitch; 2 mm x 1.25 mm x 0.95 mm body	SOT323

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
NX3008NBKW	AA %

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

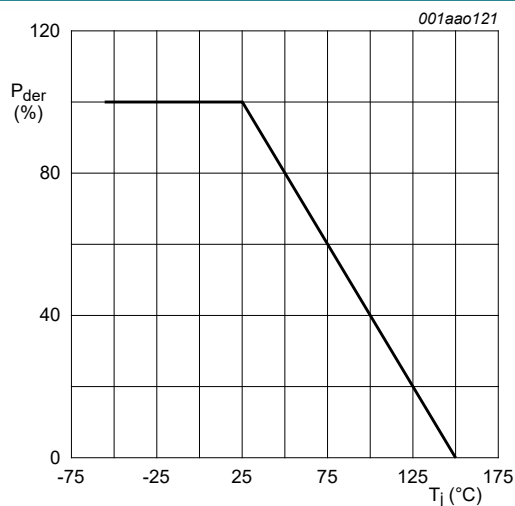
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_J = 25\text{ }^{\circ}\text{C}$		-	30	V
V_{GS}	gate-source voltage			-8	8	V
I_D	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}$	[1]	-	350	mA
		$V_{GS} = 4.5\text{ V}; T_{amb} = 100\text{ }^{\circ}\text{C}$	[1]	-	230	mA
I_{DM}	peak drain current	$T_{amb} = 25\text{ }^{\circ}\text{C}$; single pulse; $t_p \leq 10\text{ }\mu\text{s}$		-	1.4	A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ }^{\circ}\text{C}$	[2]	-	260	mW
			[1]	-	310	mW
		$T_{sp} = 25\text{ }^{\circ}\text{C}$		-	830	mW
T_J	junction temperature			-55	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	150	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	150	$^{\circ}\text{C}$
Source-drain diode						
I_S	source current	$T_{amb} = 25\text{ }^{\circ}\text{C}$	[1]	-	300	mA
ESD maximum rating						
V_{ESD}	electrostatic discharge voltage	HBM	[3]	-	2000	V

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².

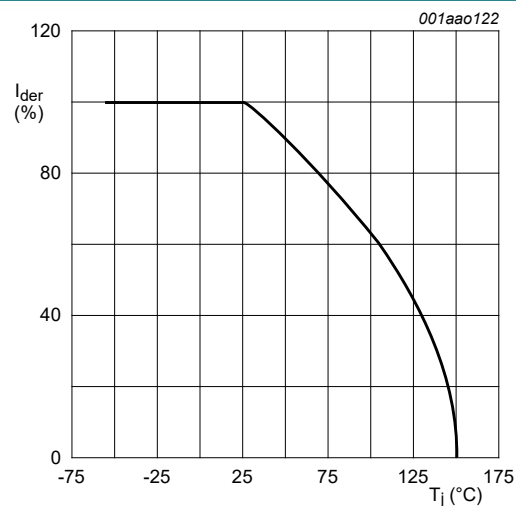
[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



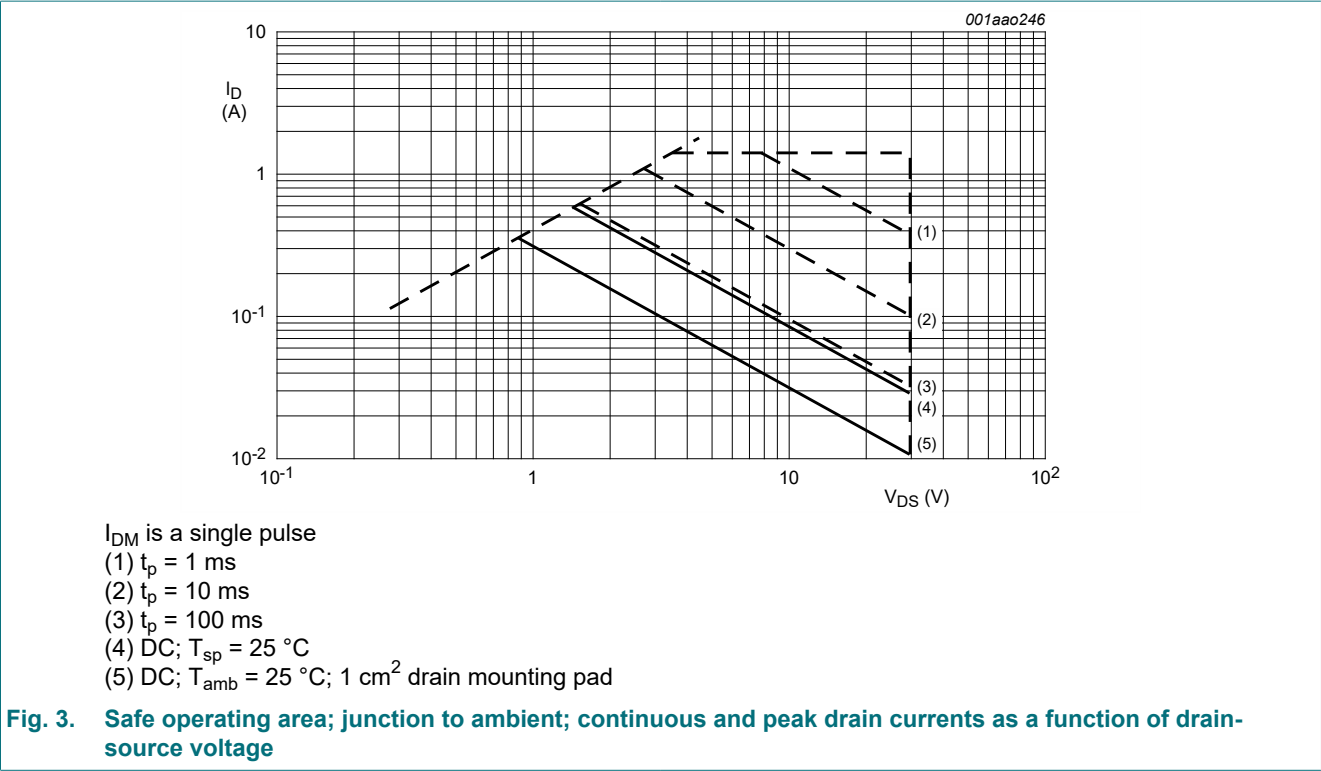
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}}$$

Fig. 1. Normalized total power dissipation as a function of junction temperature



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100\%$$

Fig. 2. Normalized continuous drain current as a function of junction temperature



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	310	370	K/W
			[2]	-	260	300	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	115	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².

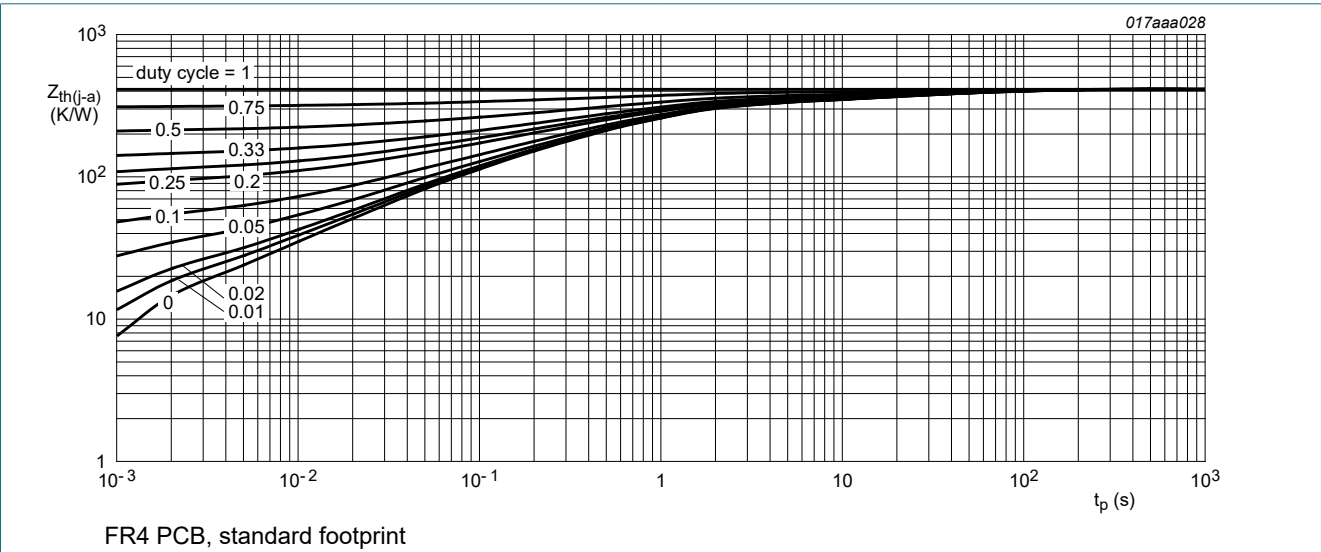


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

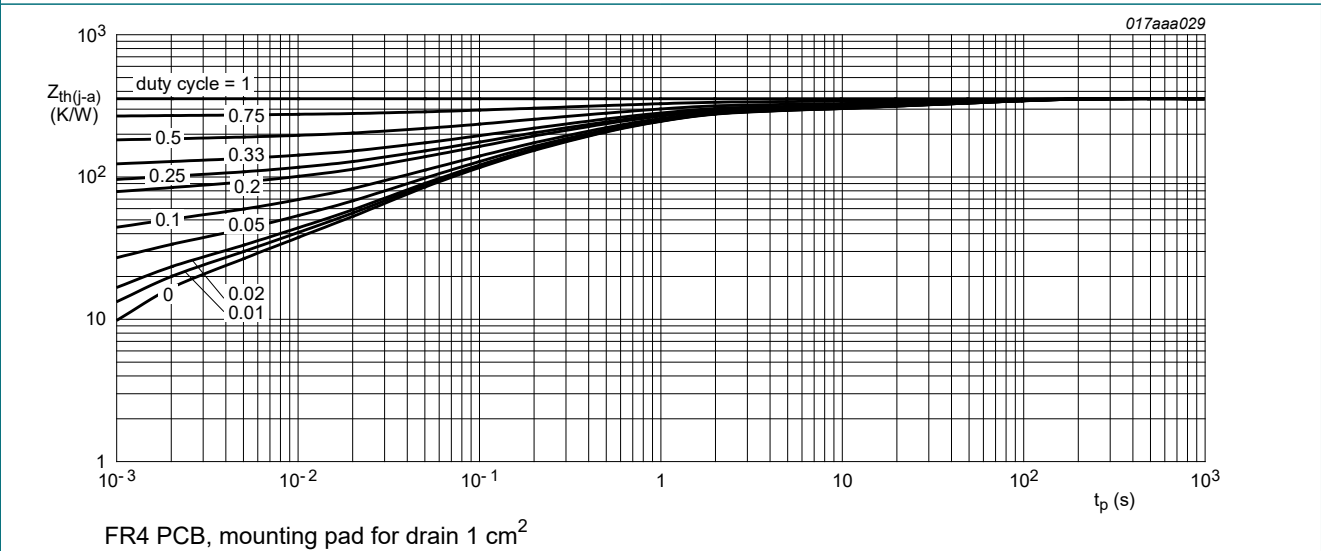


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _J = 25 °C		30	-	-	V
V _{GSth}	gate-source threshold voltage	I _D = 250 μA; V _{DS} = V _{GS} ; T _J = 25 °C		0.6	0.9	1.1	V
I _{DSS}	drain leakage current	V _{DS} = 30 V; V _{GS} = 0 V; T _J = 25 °C		-	-	1	μA
		V _{DS} = 30 V; V _{GS} = 0 V; T _J = 150 °C		-	-	10	μA
I _{GSS}	gate leakage current	V _{GS} = 8 V; V _{DS} = 0 V; T _J = 25 °C		-	0.2	1	μA
		V _{GS} = -8 V; V _{DS} = 0 V; T _J = 25 °C		-	0.2	1	μA
		V _{GS} = 4.5 V; V _{DS} = 0 V; T _J = 25 °C		-	10	-	nA
		V _{GS} = -4.5 V; V _{DS} = 0 V; T _J = 25 °C		-	10	-	nA
		V _{GS} = 2.5 V; V _{DS} = 0 V; T _J = 25 °C		-	1	-	nA
		V _{GS} = -2.5 V; V _{DS} = 0 V; T _J = 25 °C		-	1	-	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = 4.5 V; I _D = 350 mA; T _J = 25 °C		-	1	1.4	Ω
		V _{GS} = 4.5 V; I _D = 350 mA; T _J = 150 °C		-	1.8	2.5	Ω
		V _{GS} = 2.5 V; I _D = 200 mA; T _J = 25 °C		-	1.4	2.1	Ω
		V _{GS} = 1.8 V; I _D = 10 mA; T _J = 25 °C		-	2	2.8	Ω
g _{fs}	forward transconductance	V _{DS} = 10 V; I _D = 350 mA; T _J = 25 °C		-	310	-	mS
Dynamic characteristics							
Q _{G(tot)}	total gate charge	V _{DS} = 15 V; I _D = 350 mA; V _{GS} = 4.5 V; T _J = 25 °C		-	0.52	0.68	nC
Q _{GS}	gate-source charge			-	0.17	-	nC
Q _{GD}	gate-drain charge			-	0.08	-	nC
C _{iss}	input capacitance	V _{DS} = 15 V; f = 1 MHz; V _{GS} = 0 V; T _J = 25 °C		-	34	50	pF
C _{oss}	output capacitance			-	6.5	-	pF
C _{rss}	reverse transfer capacitance			-	2.2	-	pF
t _{d(on)}	turn-on delay time	V _{DS} = 20 V; R _L = 250 Ω; V _{GS} = 4.5 V; R _{G(ext)} = 6 Ω; T _J = 25 °C		-	15	30	ns
t _r	rise time			-	11	-	ns
t _{d(off)}	turn-off delay time			-	69	138	ns
t _f	fall time			-	19	-	ns
Source-drain diode							
V _{SD}	source-drain voltage	I _S = 350 mA; V _{GS} = 0 V; T _J = 25 °C		0.47	0.85	1.2	V

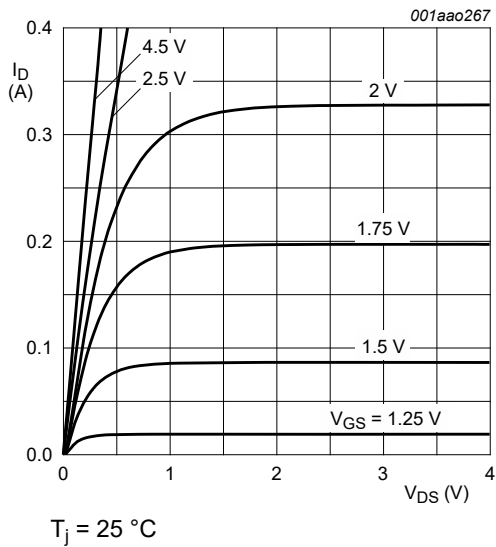


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

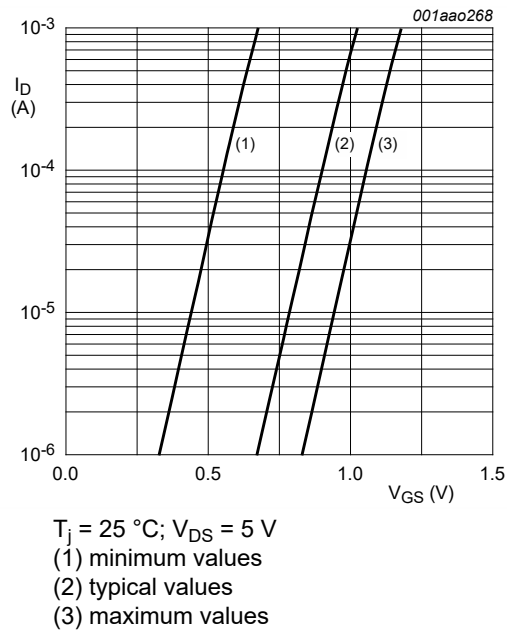


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

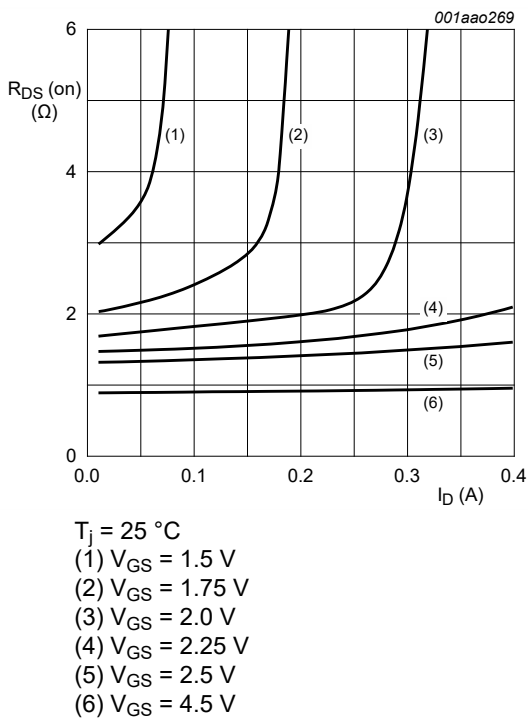


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

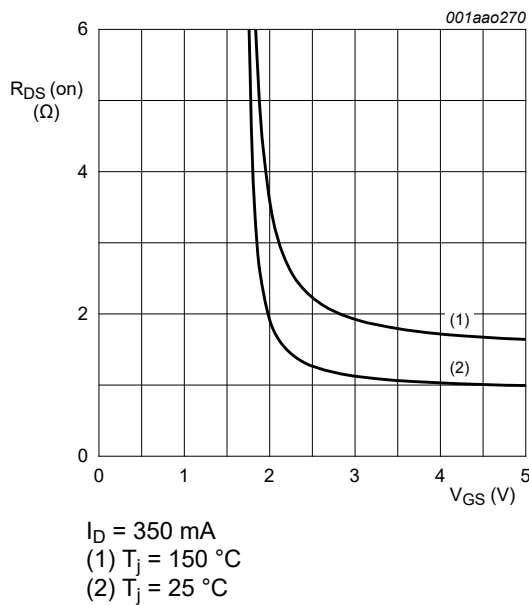


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

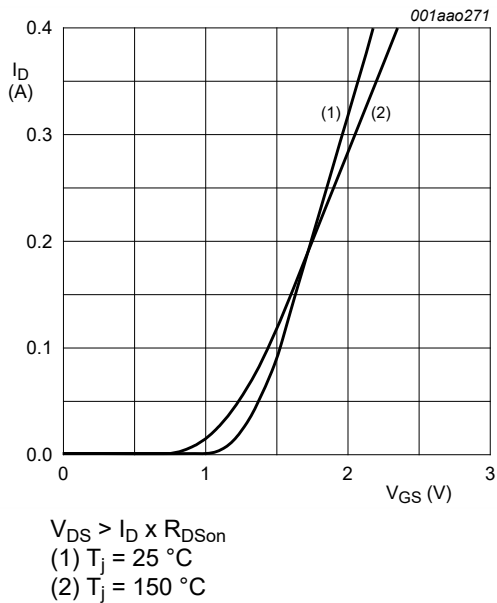


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

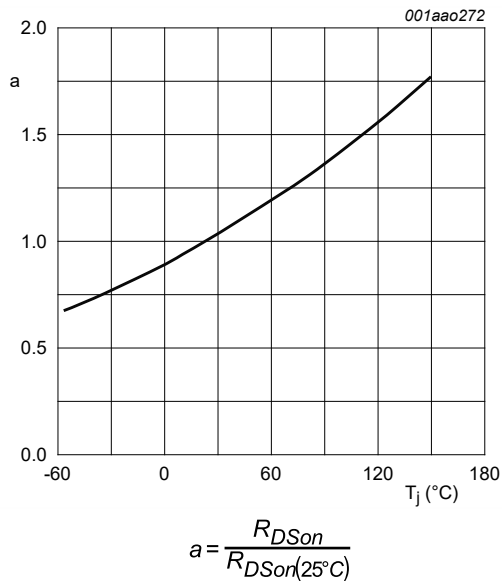


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

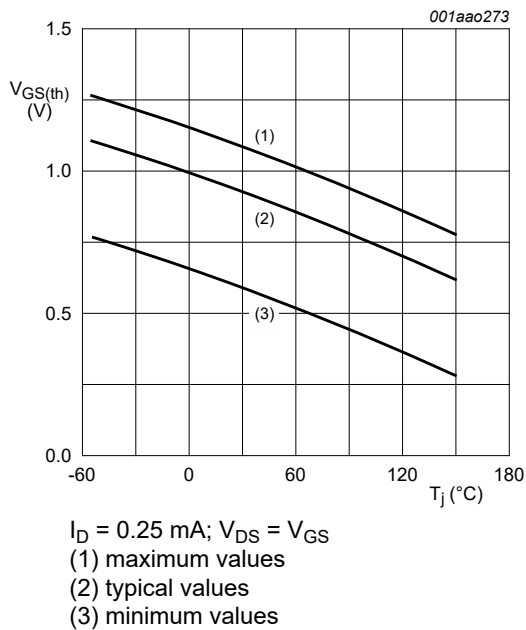


Fig. 12. Gate-source threshold voltage as a function of junction temperature

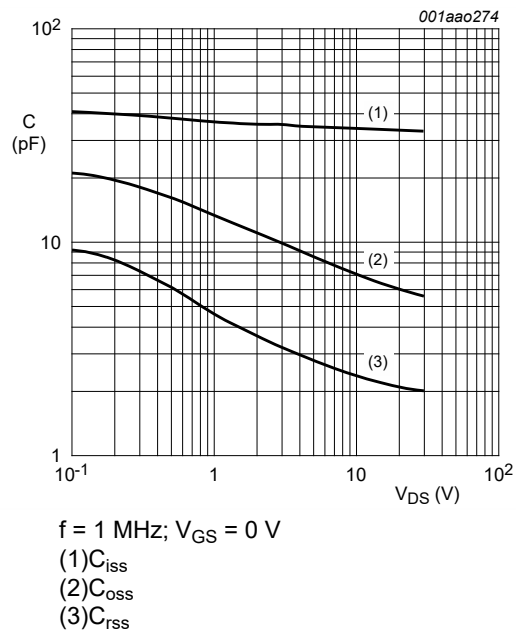


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

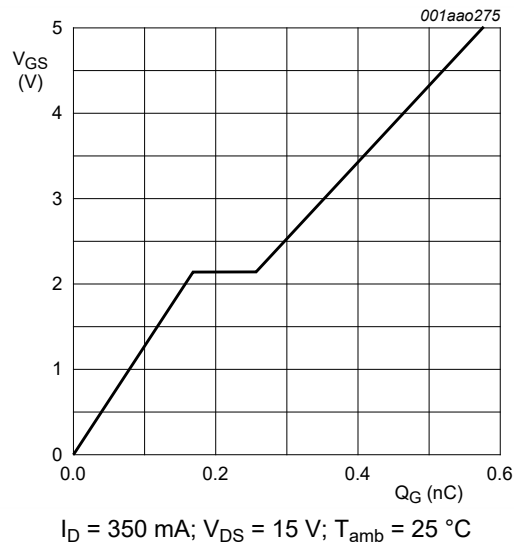


Fig. 14. Gate-source voltage as a function of gate charge; typical values

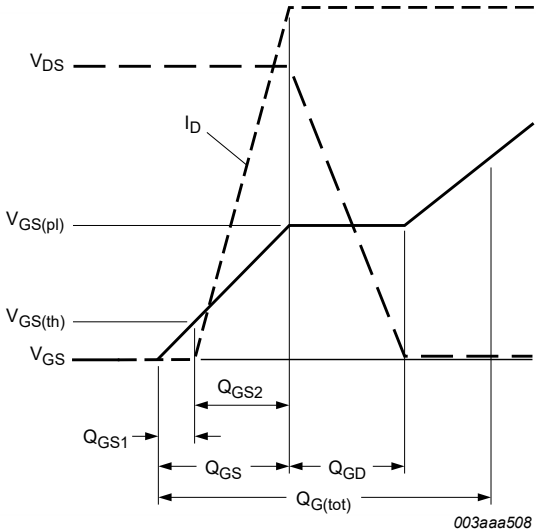


Fig. 15. Gate charge waveform definitions

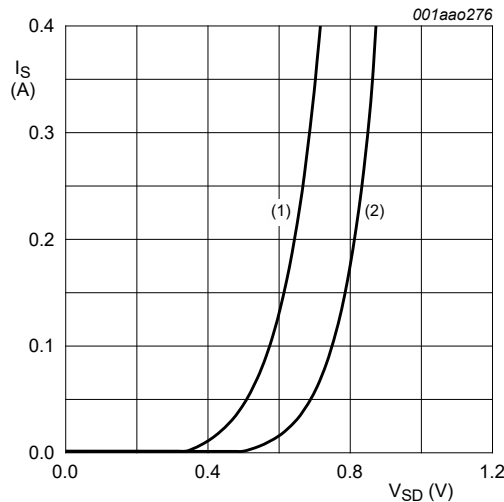


Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information



Fig. 17. Duty cycle definition

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

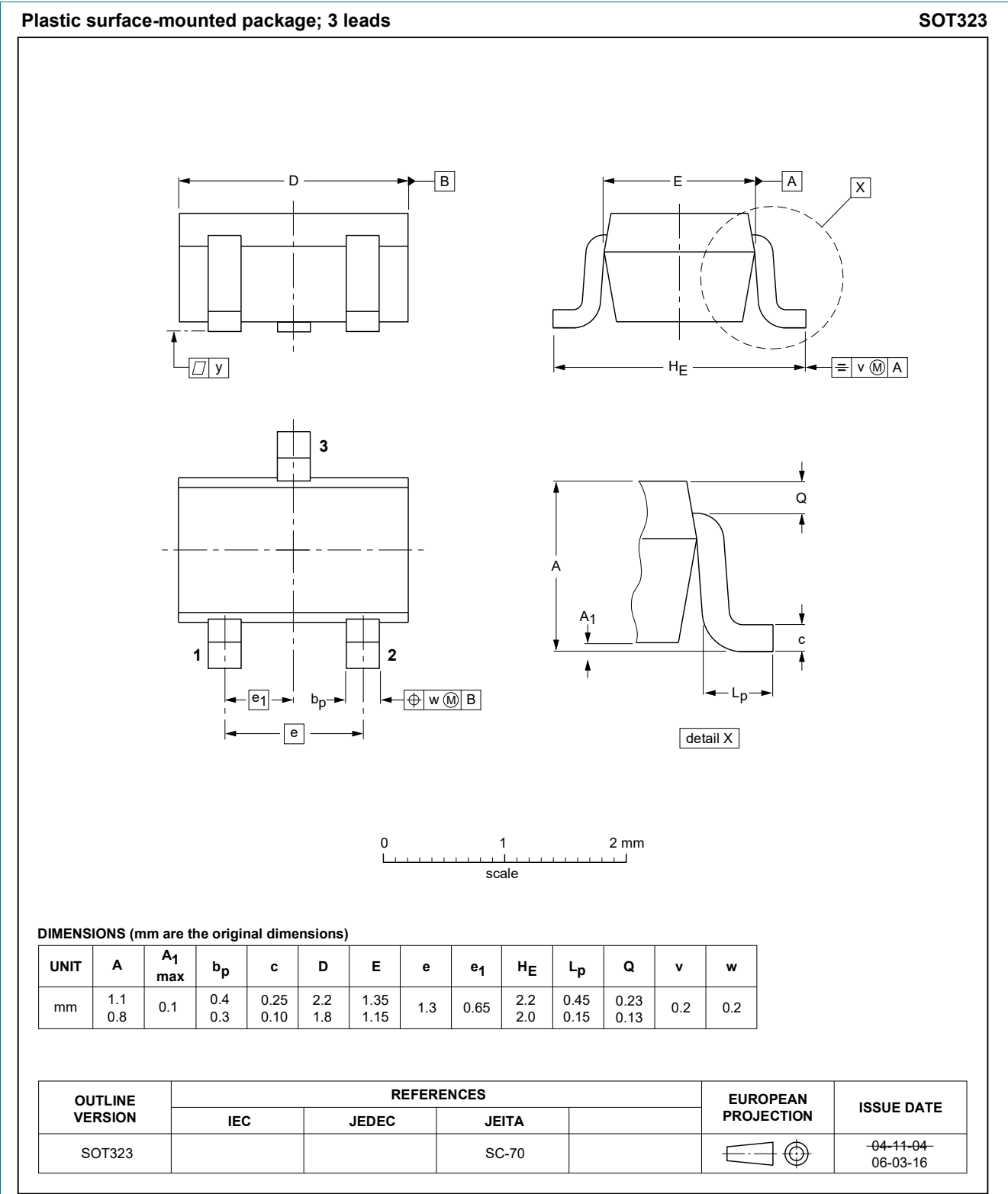
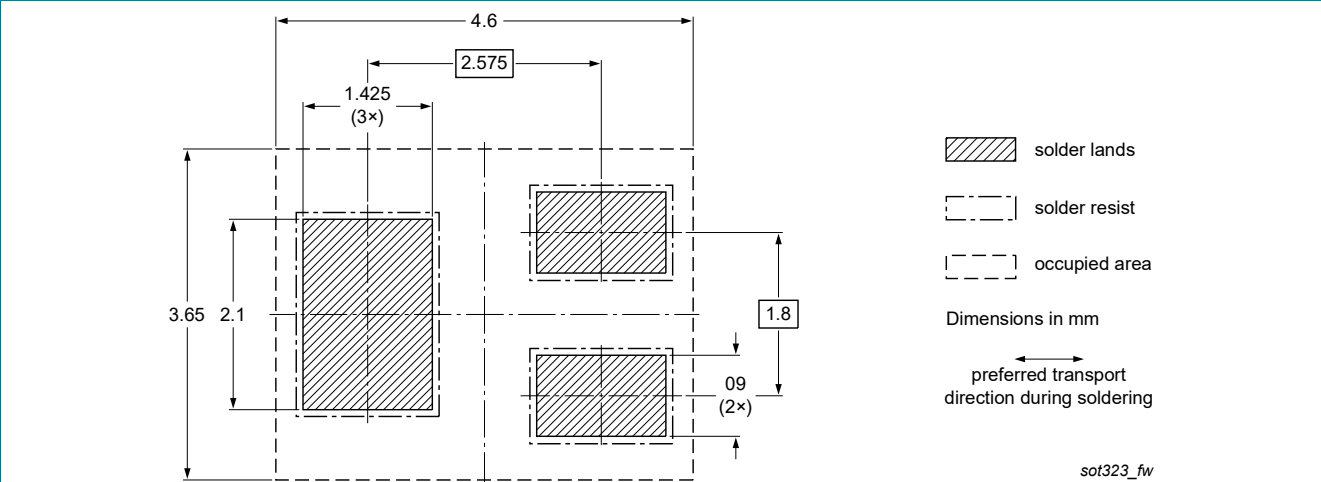
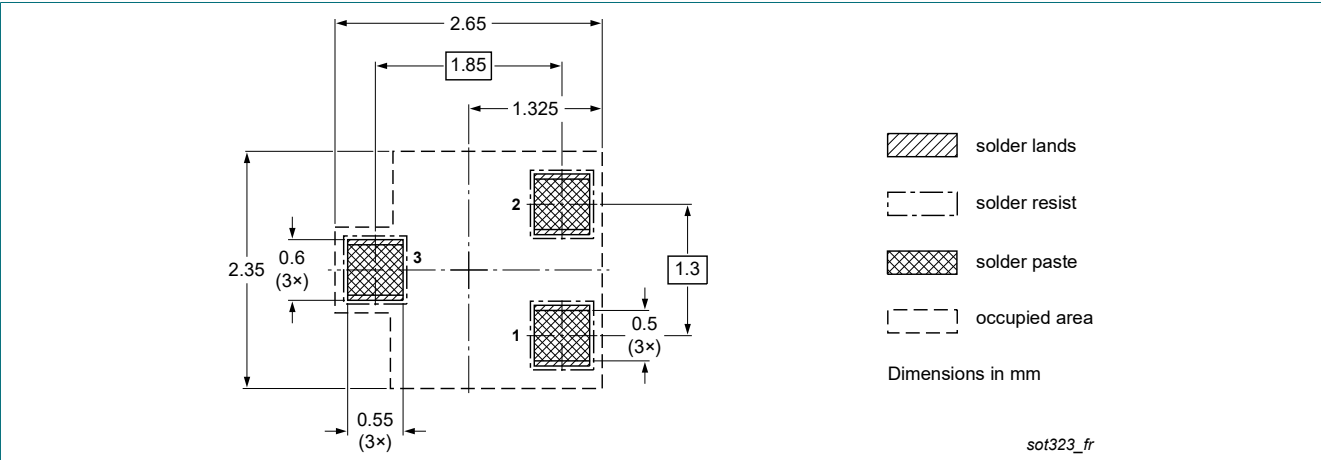


Fig. 18. Package outline SC-70 (SOT323)

13. Soldering



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
NX3008NBKW v.2	20221105	Product data sheet	-	NX3008NBKW v.1
Modifications:	• Chapter "Characteristics": typo correction, V_{SD} axis scaling for Fig. 16 revised			
NX3008NBKW v.1	20110802	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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